

ABSTRACT OF THE DISCLOSURE

A deposited film forming apparatus ~~is provided~~
which has a power applying electrode disposed above a
flat plate type base member grounded, in a vacuum
5 chamber, and a power source for supplying a power to
the power applying electrode, the deposited film
forming apparatus being constructed to supply the power
from the power source to the power applying electrode
so as to generate a plasma in a discharge space between
10 the power applying electrode and a substrate disposed
in opposition to the power applying electrode in the
vacuum chamber and serving as an electrode in a pair
with the power applying electrode, thereby decomposing
a source gas introduced into the vacuum chamber to form
15 a deposited film on the substrate, wherein the power
applying electrode is fixed to the base member with the
power applying electrode being isolated from the base
member. ~~A deposited film forming method using the
apparatus is also provided. This permits the power
20 applying electrode to be fixed to the base member while
isolating the power applying electrode from the base
member, thereby preventing deformation of the power
applying electrode. As a consequence, occurrence of
plasma intrusion or abnormal discharge is prevented
25 between the power applying electrode and the base
member.~~